







### **Product Outline:**

This is the high efficiency LED with reflector type. EMC 3030 Single color is a surfacemount LED which with heat sink to enhance operating performance. With special binning technology, these LEDs are ideal for architecture lighting and special lighting needs.

## Features:

- Green color
- High brightness output @ 150mA,
- High driving current to 200mA.
- Package Dimension = 3.2mmX3.0mmX0.6mm
- RoHS compliant
- Custom Bin available upon special request

## **Application:**

- Warning lamp
- Decoration lamp
- Architecture Lighting
- Garden Lighting
- Horticulture Lighting

### **Compliance and Certification:**



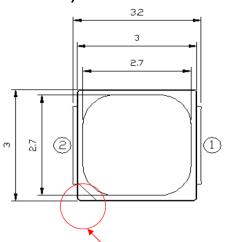


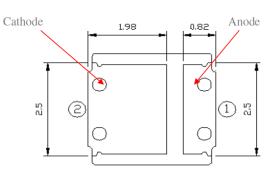


## **Mechanical Property:**



0.6



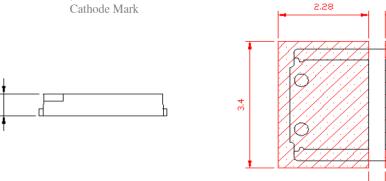


Recommended Solder Pad Design

1.12

0,4

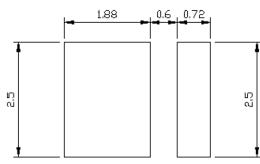
84 4



\* All dimensions are in millimeters, \* Tolerances are ± 0.10mm.

Tolerances are  $\pm 0.1011111$ .

## **Recommended Solder footprint:**



\* All dimensions are in millimeters.

- \* The LEDs is designed to be reflow soldered on to a PCB. IF dip soldered that QL cannot guarantee its reliability.
- \* Reflow soldering must not be performed more than twice.



# **Characteristics**

Absolute	Maximu	m Ratings

Absolute Maximu	(Ta=25℃)		
Parameter	Symbol	Rating	Unit
DC Forward Current	lf	200	mA
Leakage Current	lr	1.0	μA
Power Dissipation	Pd	0.6	W
Pulse Forward Current	lfp	240	mA
LED Junction Temperature	TJ	125	°C
Storage Temperature	Tstg	-40 ~ 100	°C
Operation Temperature	Topr	-40 ~ 85	°C
Soldering Temperature	Tsol	260 < 10 sec	°C
ESD Sensitivity(HBM)		8	KV
Thermal Resistance	Rth	10	°CW

(1) Proper current rating must be observed to maintain junction temperature below maximum at all time(2) IFP Condition: Duty 1/10, Pulse within 10msec

#### **Electrical / Optical Characteristic**

(Ta=25 oC)

Product	Color I <sub>F</sub> (mA)		V <sub>F</sub> (V)		Wavelength		htness n/mW)
			Тур.	max	nm	min	typ.
QLSP04GKH	Green	150	3.0	3.5	515~530	30 lm	40 lm





## Groups

Dominant Wavelength

Wd (nm) @ 150mA					
Color Code name Min. Max.					
	DM	515	520		
Green	DN	520	525		
	DP	525	530		

Measurement tolerance is +/- 1nm

#### Forward Voltage (V<sub>F</sub>) Bin:

VF Rank @ 150mA (Vf)						
Color	Code name	Low	High			
	01	2.8	3.0			
Croop	23	3.0	3.2			
Green	45	3.2	3.4			
	67	3.4	3.6			

The forward voltage tolerance is  $\pm 0.1V$ 

#### Luminous Flux Bin:

Rank @ 150mA (Im)					
Color	Code name	Low	High		
	QK	22.5	25		
Green	QL	25	28		
	QM	28	31.5		

luminous flux tolerance is ± 7%

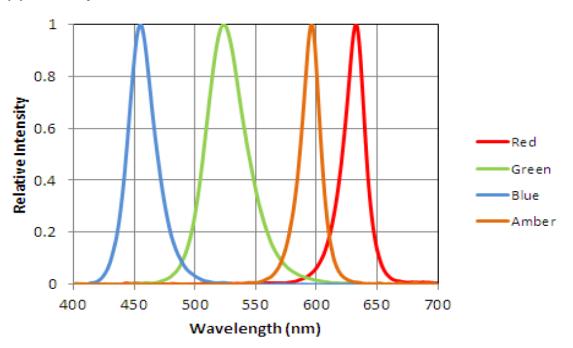




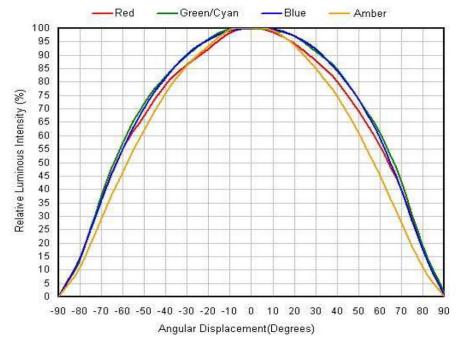
QLSP04GKH V1.0

**Characteristic Curves** 

(1) Color Spectrum



#### (2). Typical Representative Spatial Radiation Pattern

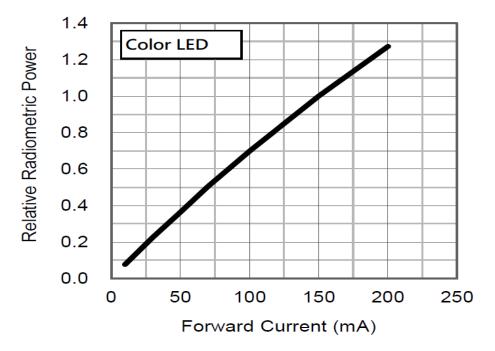




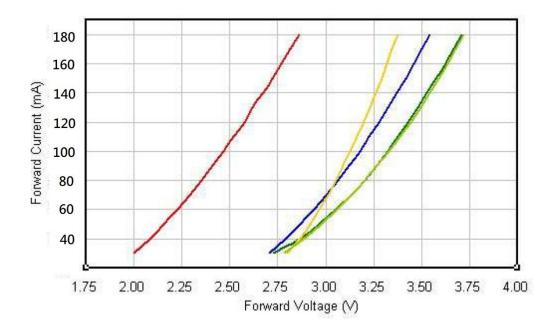




#### (3). Forward Current Characteristics



#### (4). Forward Current vs Forward Voltage





## Reliability test:

No	Item	Condition	Time/Cycle	Sample size
1	Steady State Operating Life of Room Temperature	25°C Operating	1000 Hrs	20 pcs
2	Steady State Operating Life of Low Temperature -40 $^\circ\!\!\mathbb{C}$	-40°C Operating	1000 Hrs	20 pcs
3	Steady State Operating Life of Low Temperature $60^\circ\!\mathrm{C}$	60℃ Operating	1000 Hrs	20 pcs
4	Steady State Operating Life of Low Temperature $85^\circ\!\!\mathbb{C}$	85°C Operating	1000 Hrs	20 pcs
5	Low temperature storage -40 $^\circ\!\!\!\!\!^\circ$	-40°C Storage	1000 Hrs	20 pcs
6	High temperature storage 100 $^\circ\!\mathrm{C}$	100°C Storage	1000 Hrs	20 pcs
7	Steady State Operating Life of High Humidity Heat $60^\circ\!\!\!\!C90\%$	60°C/90% Operating	1000 Hrs	20 pcs
8	Steady State Pulse Operating Life Condition	$25^{\circ}$ C 10Hz duty=1/10 Operating	200 Cycle	20 pcs
9	Resistance to soldering heat on PCB (JEDEC MSL3)	pre-store@60℃, 60%RH for 52hrs Tsld max.=260 10sec	3 Times	20 pcs
10	Heat Cycle Test (JEDEC MRC)	25℃~65℃~-10℃, 90%RH, 24hr/1cycle	10 Cycle	20 pcs
11	Thermal shock	-40℃/ 20minr~ 5minr~100℃ /20min	300 Cycle	20 pcs

## Judgment Criteria:

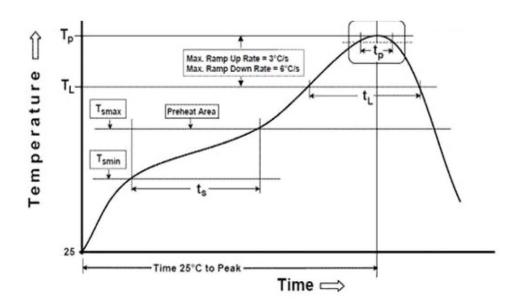
ltem	Symbol	Test Condition	Judgment Criteria
Forward Voltage	Vf	150 mA	∆Vf< 10%
Luminous Flux	lv	150 mA	<b>∆Iv&lt; 30%</b>





### **Solder Profile:**

-The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

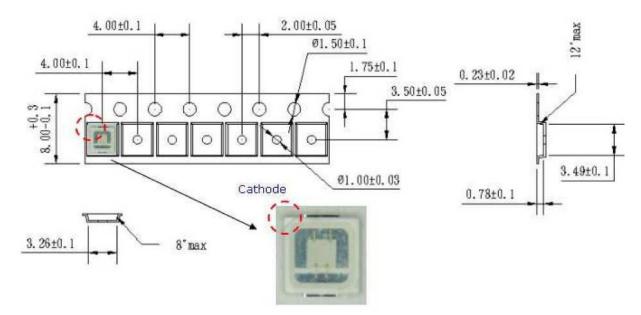


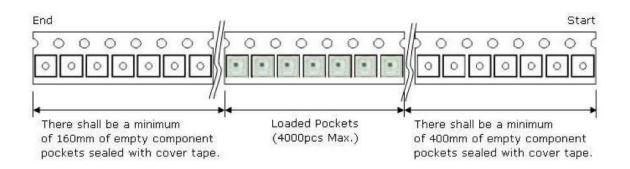
Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Temperature Min(T <sub>smin</sub> )	100°C	<b>150</b> ℃
Temperature Max(T <sub>smax</sub> )	<b>150</b> ℃	<b>200</b> ℃
Time(t <sub>a</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds	60-120 seconds
Ramp-up rate( $T_L$ to $T_P$ )	3℃/second max.	3℃/second max.
Liquidous Temperature(T <sub>L</sub> )	<b>183</b> ℃	<b>217</b> ℃
Time( $t_L$ ) maintained above $T_L$	60-150 seconds	60-150 seconds
Peak package body temperature( $T_P$ )	235℃	260℃
Time within 5° $_{\mathbb C}$ of Actual Peak	20	20
temperature (t <sub>p</sub> )	20seconds*	30 seconds*
Ramp-down rate( $T_P$ to $T_L$ )	6℃/second max.	6℃/second max.
Time 25 $^\circ\!$	6 minutes max.	8 minutes max.

 $^*$  Tolerance for peak profile temperature (T\_P) is defined as a supplier minimum and a user maximum.



### Taping & Packing:

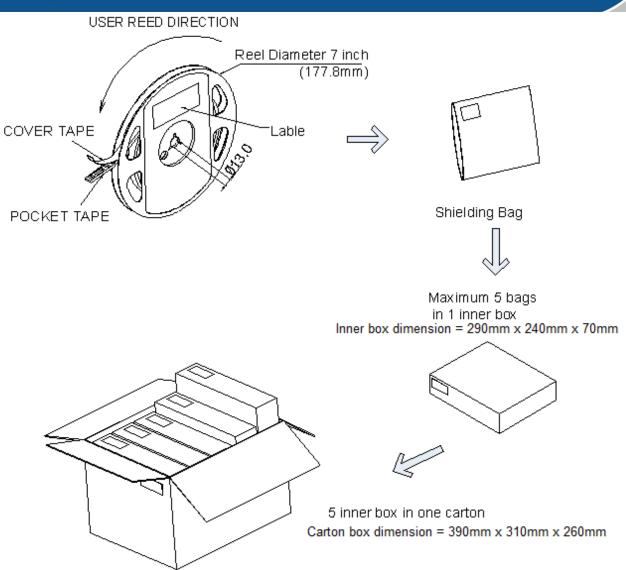




Unit : mm











## Labeling

Quantity: XX	<b></b>	QueLighting
	P/N: XXXXXX	

## Ordering Information:

Part #	Multiple Quantities	Quantity per Reel
QLSP04GKH		1000, 2000 pcs

## **Revision History:**

Revision Date:	Changes:	Version #:
09-21-2020	Initial release	1.0